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BUMP ELECTRODE BOND-FORMATION METHOD

Inventor: Toshio Yamagata,
NEC,
5-33-1 Shiba, Minato-ku,
Tokyo

Applicant: NEC,
5-33-1 Shiba, Minato-ku,
Tokyo

Agent: Susumu Uchihara, patent
attorney

[There are no amendments to this patent.]

Claim

Bump electrode bond-formation method characterized in that, in a bump electrode bond-formation method wherein a pair of semiconductor chips, on the surface of each of which a bump electrode is provided, are bonded with the aforementioned bump electrodes facing each other, each of the aforementioned bump electrodes corresponding to the aforementioned pair of semiconductor chips is placed so that their perimeters will overlap each other and each of the corresponding aforementioned bump electrodes are bonded so that the centers of said bump electrodes will intrude into each other so that the aforementioned overlapping portions will be crushed.

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